

### ABSTRACT

A method is provided to suppress detachment between semiconductor packages while preventing dislocation at the time of mounting a stacked semiconductor package on a motherboard. Semiconductor packages PK1 and PK2 are bonded to each other through protruding electrodes and resin is provided between the semiconductor packages PK1 and PK2. The resin is provided in the peripheries of the protruding electrodes so as to contact each of the protruding electrodes while not contacting a semiconductor chip.